



# SPN4842 N-Channel Enhancement Mode MOSFET

## DESCRIPTION

The SPN4842 is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching .

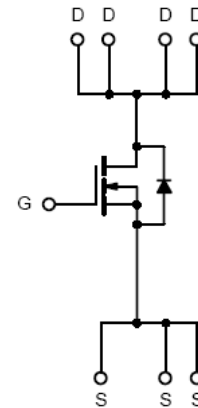
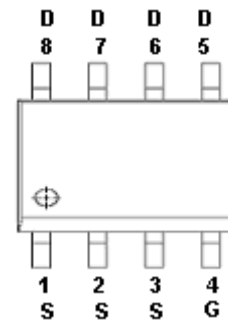
## FEATURES

- ◆ 45V/6A,  $R_{DS(ON)}=9.5m\Omega@V_{GS}=10V$
- ◆ 45V/3A,  $R_{DS(ON)}=12.5m\Omega@V_{GS}=4.5V$
- ◆ Super high density cell design for extremely low  $R_{DS(ON)}$
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ SOP – 8P package design

## APPLICATIONS

- DC/DC Converter
- Load Switch
- Synchronous Buck Converter
- Charger Adapter
- LED Lighting

## PIN CONFIGURATION(SOP – 8P)



## PART MARKING





# SPN4842

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### PIN DESCRIPTION

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

### ORDERING INFORMATION

Part Number	Package	Part Marking
SPN4842S8RGB	SOP-8P	SPN4842

※ SPN4842S8RGB : 13" Tape Reel ; Pb – Free ; Halogen – Free

### ABSOLUTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V <sub>DSS</sub>	45	V
Gate –Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub>	TA=25°C	13.3
		TA=100°C	8.4
Pulsed Drain Current	I <sub>DM</sub>	53.2	A
Single Pulse Avalanche Energy	E <sub>AS</sub>	38	mJ
Avalanche Current	I <sub>AS</sub>	27	A
Power Dissipation	P <sub>D</sub>	TA=25°C	2.5
		TA=70°C	1.4
Operating Junction Temperature	T <sub>J</sub>	-55/150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	50	°C/W



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### ELECTRICAL CHARACTERISTICS

(TA=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit		
<b>Static</b>								
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	45			V		
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0		2.5			
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$			$\pm 100$	nA		
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=45V, V_{GS}=0V, T_J=25^\circ C$			1	$\mu A$		
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=6A$		6	9.5	$m\Omega$		
		$V_{GS}=4.5V, I_D=3A$		8	12.5			
Forward Transconductance	$g_{fs}$	$V_{DS}=5V, I_D=6A$		25		S		
Diode Forward Voltage	$V_{SD}$	$I_S=13.3A, V_{GS}=0V$			1.5	V		
<b>Dynamic</b>								
Total Gate Charge	$Q_g$	$V_{DS}=20V, V_{GS}=10V$ $I_D=13.3A$		31.5		nC		
Gate-Source Charge	$Q_{gs}$			3.5				
Gate-Drain Charge	$Q_{gd}$			9				
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V$ $f=1MHz$		1600		pF		
Output Capacitance	$C_{oss}$			180				
Reverse Transfer Capacitance	$C_{rss}$			130				
Turn-On Time	$t_{d(on)}$	$V_{DD}=20V,$ $I_D=13.3A, V_{GS}=10V$ $R_G=6\Omega$		12		nS		
	$t_r$			82				
Turn-Off Time	$t_{d(off)}$			33				
	$t_f$			59				
Gate resistance	$R_g$		$V_{GS}=0V, V_{DS}=0V, f=1MHz$		1.2			$\Omega$

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=50V, V_{GS}=10V, L=0.1mH, I_{AS}=27A, R_G=25\Omega, \text{Starting } T_J=25^\circ C$
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.



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## TYPICAL CHARACTERISTICS

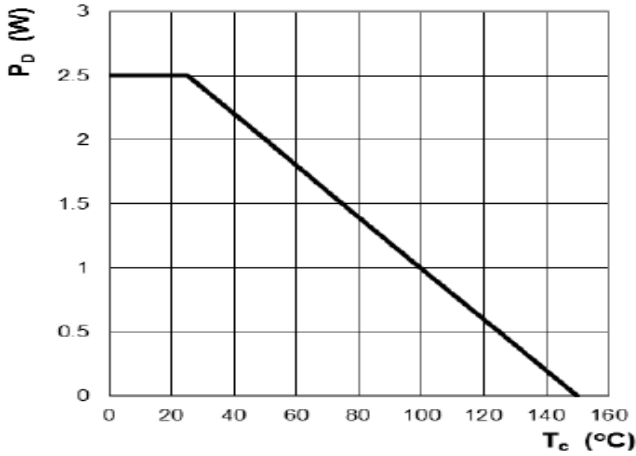


Figure 1: Power Dissipation

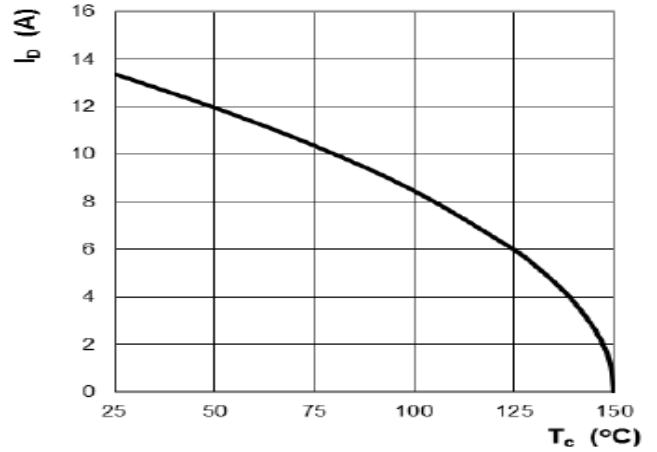


Figure 2: Continuous Drain Current vs.  $T_c$

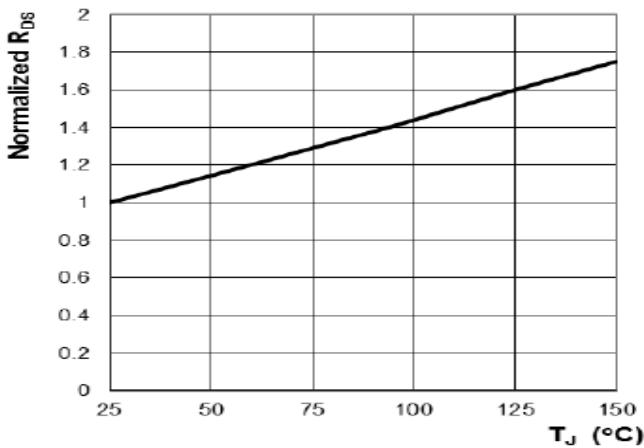


Figure 3: Normalized  $R_{DS(on)}$  vs.  $T_J$

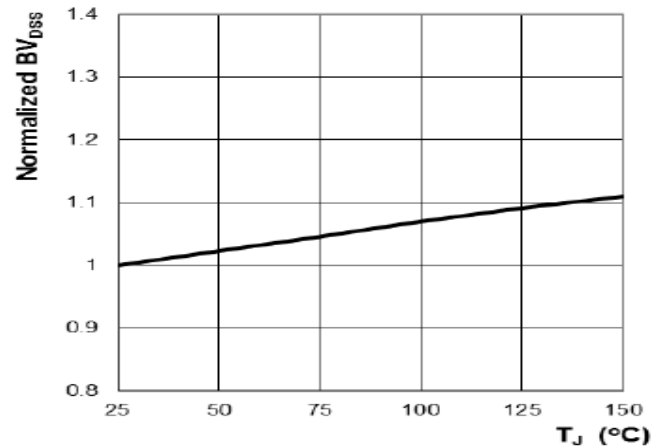


Figure 4: Normalized  $BV_{DSS}$  vs.  $T_J$

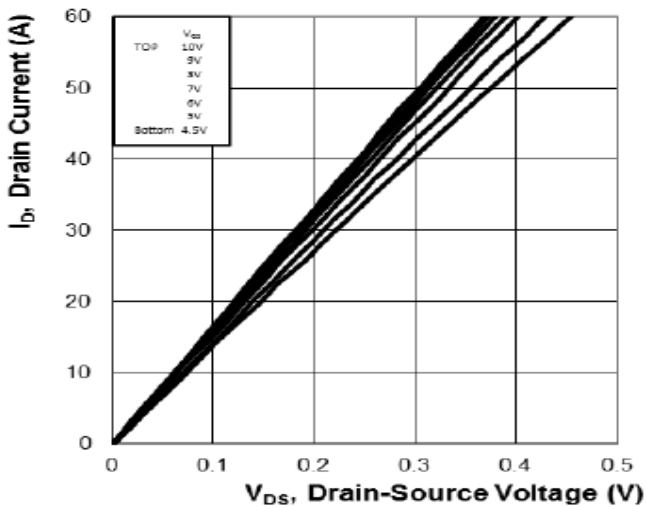


Figure 5: On-Region Characteristics

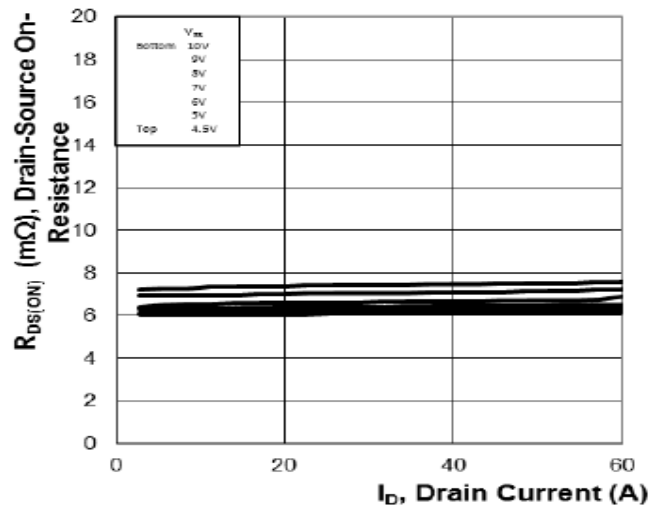


Figure 6: Typ.  $R_{DS}$  Variation vs.  $I_D$  and  $V_{GS}$



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## TYPICAL CHARACTERISTICS

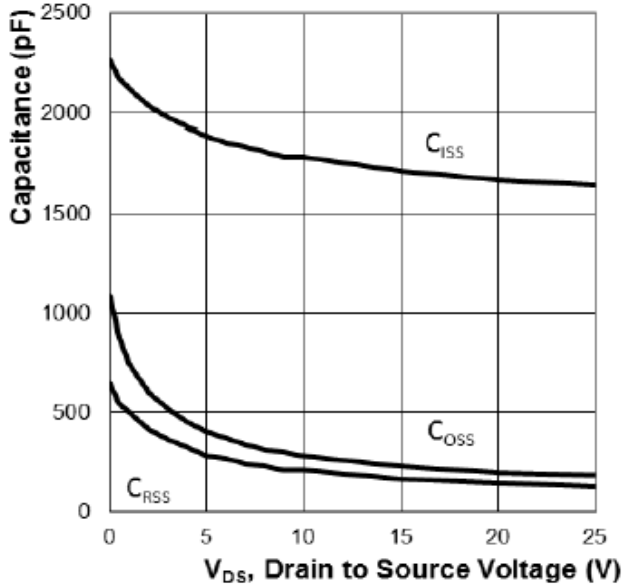


Figure 7: Typ. Capacitance Characteristics

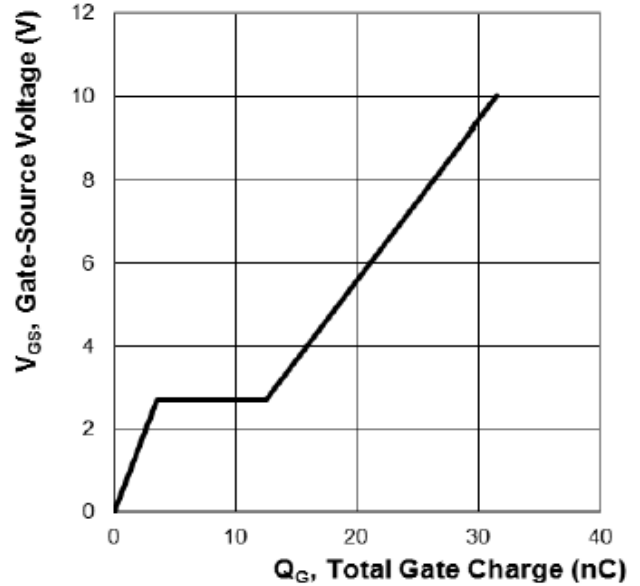


Figure 8: Typ. Gate Charge Characteristics

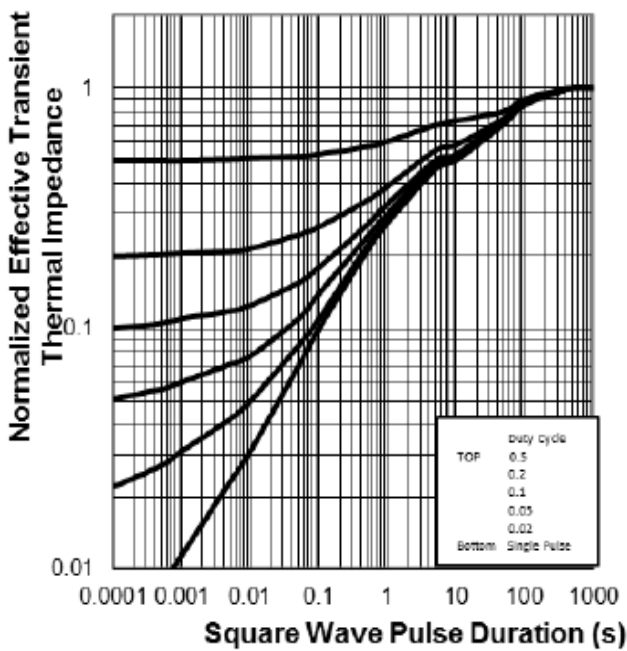


Figure 9: Normalized Thermal Transient Impedance, Junction-to-Case

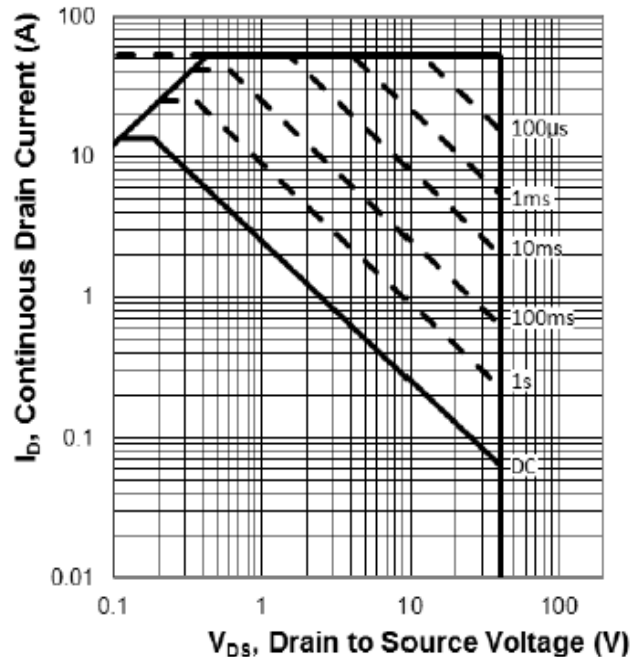


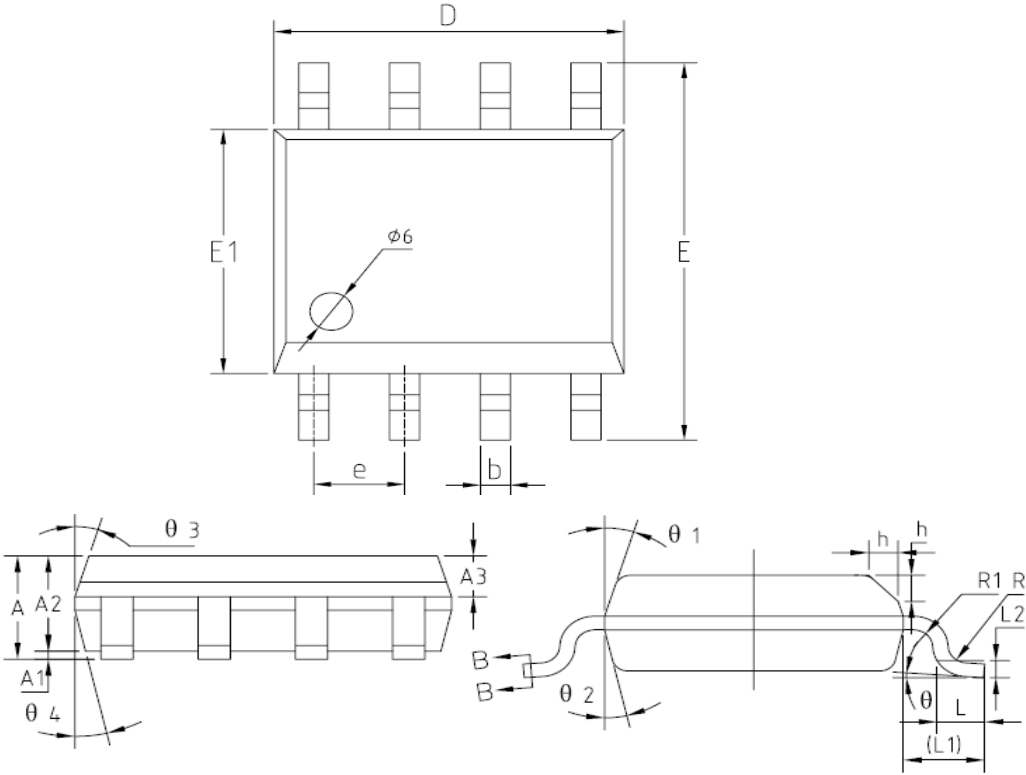
Figure 10: Maximum Safe Operation Area



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### SOP- 8 PACKAGE OUTLINE



SYMBOL	MIN	NOM	MAX
A	1.35	--	1.75
A1	0.10	--	0.25
A2	1.25	1.40	1.65
A3	0.50	0.60	0.70
b	0.33	-	0.51
c	0.17	--	0.25
D	4.80	4.93	5.05
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.17	1.27	1.37
L	0.45	0.60	0.80
L1	1.04 REF		
L2	0.25BSC		
R	0.07	--	--
R1	0.07	--	0.20
h	0.25	--	0.50
θ	0°	--	8°
θ 1	15°	17°	19°
θ 2	11°	13°	15°
θ 3	15°	17°	19°
θ 4	11°	13°	15°



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